

THERMOCOMPTM HMD D SERIES: THIN, LIGHT, AND STRONG

SOLUTION STORY: ELECTRONICS

HIGHLIGHTS

- Good strength for metal replacement
- Good flow-ability for thin-wall design
- Weight reduction
- · Non bromide / Non chloride flame retardant
- Good surface aesthetics

SHORT STORY

THERMOCOMP HMD-D portfolio provides our customers with a solution to achieve challenging structural design. This portfolio can deliver high ductility, long-term aging, dimensional stability, and can maintain good surface aesthetics.

This excellent material can offer a broad design space to balance ductility, modulus, and surface quality, with more robust processing vs. glass-filled compounds. They are specifically engineered for challenging structural components in the consumer electronics, healthcare, and transportation sectors. The THERMOCOMP HMD-D product family can help customers lower total system cost by supporting part integration, process simplification, and potential elimination of secondary operations, such as painting.

CONTACT US

Reach out to learn more about electronic solutions from SABIC.

Email us at npeinquiries@sabic.com.

© 2018 Copyright by SABIC. All rights reserved. SABIC and brands marked with TM are trademarks of SABIC or affiliates.

NPE2018-ELEC-thermocomp-hdm-d-series